

ALPHA[®] OM-535

Low Melting Point, No-Clean Lead-Free, Halogen-Free Solder Paste for Double Sided Single Reflow Application

DESCRIPTION

ALPHA OM-535 is a Low Temperature Solder Paste Technology Designed to Enable a Single Reflow Application for Assembly of Double Sided Board. Its key attribute is excellent no-solder drip phenomena during the reflow process. **ALPHA OM-535** solder paste version with ALPHA SBX02 alloy, melting point below 140 °C, has been successfully used with peak reflow profiles between 155 °C and 190 °C. ALPHA SBX02 alloy has higher Mechanical Strength and Drop Shock Resistance than the SnBi0.4Ag alloy. The flux residue from **ALPHA OM-535** provides excellent electrical resistivity, exceeding industry standards.

This product enables the elimination of an extra wave or selective wave soldering process when temperature sensitive through-hole components are used in an assembly. Benefits include; increased daily throughput, eliminating the need for managing bar solder and wave soldering flux supplies, and eliminating the need for pallets. In addition, it removes the need for an extra SMT process. These eliminations can significantly lower the cost of producing an electronic assembly. The alloys yield very low voiding BGA solder joints, even when a traditional SAC alloy sphere is used.

All components used with **ALPHA OM-535** must be lead-free to eliminate the formation of tin/lead/bismuth phase which has a melting point under 100 °C.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

- Enables elimination of a second or third reflow cycle when temperature sensitive components or connectors are used.
- Reduces energy consumption in reflow ovens versus standard lead free alloys.
- Reduces reflow process cycle time.
- Delivers 8+ Hour stencil life.
- Potential elimination of bar solder, wave soldering flux, and energy costs associated with wave soldering.
- Compatible with all commonly used lead free surface finishes (ENTEK HT; Alpha Star Immersion Silver, Immersion Tin, Ni/Au, SACX HASL, etc.)
- Excellent resistance to random solder balling, minimizing rework and increasing first time yield.

- Low temperature reflow profiles may enable the use of less expensive printed circuit board substrates.
- Delivers very high in-circuit pin test yields, minimizing costly false negative test results.
- Compatible with either nitrogen or air reflow.
- Possesses excellent solder drip resistance during reflow.

PRODUCT INFORMATION

<u>Alloys:</u>	ALPHA SBX02, SnBi0.4Ag, 42Sn57Bi1Ag
<u>Powder Size:</u>	Type 4
<u>Packaging Sizes:</u>	500 gram jars, 6" & 12" cartridges
<u>Lead Free:</u>	RoHS Directive EU/2015/863; amending Annex II of 2011/65/EU

TECHNICAL DATA

Category	Results	Procedures/Remarks
Chemical Properties		
Activity Level	ROL0	IPC J-STD-004B
Halide Content	Halogen free	IPC J-STD-004B
Fluoride Spot Test	Pass	JIS-Z-3197-1999 8.1.4.2.4
Halogen Test	Halogen free	EN14582, by oxygen bomb combustion, Non-detectable (ND) at < 50 ppm
Copper Mirror Test	Pass	JIS Z 3197:1999 8.4.2
Copper Corrosion Test	Pass	JIS Z 3197:1999 8.4.1
Electrical Properties		
SIR (JIS Z 3197 @ 40 °C/90%RH 168 hrs)	> 10 ¹⁰ ohms	JIS Z 3197:2012
Electromigration (JIS Z 3197 @ 85 °C/85%RH 45 to 50V DC 1000 hours)	Final Reading > 10 ⁸ ohms No Migration After 1000 hrs	JIS Z 3197:2012
Physical Properties		
Color	Light yellow ~ Yellow residue	
Tack Force	148gf after 24hours	JIS Z 3284:1994, Annex 9

Category	Results	Procedures/Remarks
Viscosity	89% T4 metal powder load designated M19 for printing	Malcom Spiral Viscometer; J-STD-005
Solder Ball	Level 2 (JIS method)	JIS Z 3284, Annex 11
Cold/Printing Slump	0.2mm gap open	JIS Z 3284:2014 4.3
Hot Slump: 128 °C for 10 to 20min	0.3mm gap open	JIS Z 3284:2014 4.4

PROCESSING GUIDELINES

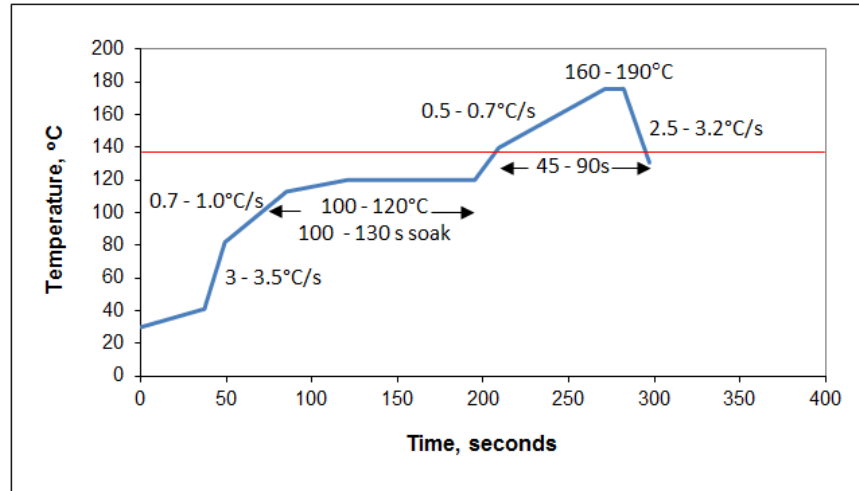
Printing

Stencil: Recommend ALPHA CUT, ALPHA NICKEL-CUT, ALPHA TETRABOND, or ALPHA FORM stencils @ 0.100 to 0.150 mm (4 to 6 mil) thick for 0.4 to 0.5 mm (0.016" or 0.020") pitch. Stencil design is subject to many process variables. Contact your local ALPHA stencil site for advice.

- Squeegee: Metal recommended
- Pressure: 0.21 to 0.36 kg/cm of blade (1.25 to 2.0 lbs/inch)
- Speed: 25 to 100 mm per second (1 to 6 inches per second)
- Paste Roll: 1.5 to 2.0 cm diameter and make additions when roll reaches 1 cm (0.4") diameter (min). Max roll size will depend upon blade
- Stencil Release Speed: 1 to 5 mm/second
- Lift Height: 8 to 14 mm(0.31 to 0.55")

REFLOW PROFILES

ALPHA OM-535 SBX02, SnBi0.4Ag Typical Reflow Profile



Please take note that this is only a typical recommendation. While it is beneficial to start off with these parameters, an open mindset is important in working out any adjustment necessary for optimized performance

RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams.

Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area or [link here](#).



SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at MacdermidAlpha.com/assembly-solutions/knowledge-base.**

STORAGE

ALPHA OM-535 should be stored in a refrigerator upon receipt at 0 to 10 °C (32 to 50 °F). ALPHA OM-535 should be permitted to reach room temperature before unsealing its package prior to use. This will prevent moisture condensation build up in the solder paste. Do not remove worked paste from stencil and mix with unused paste in jar. This will alter rheology of unused paste.

CONTACT INFORMATION

To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

www.macdermidalpha.com

<p>North America 109 Corporate Blvd. South Plainfield, NJ 07080, USA 1.800.367.5460</p>	<p>Europe Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400</p>	<p>Asia 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong 852.3190.3100</p>
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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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